

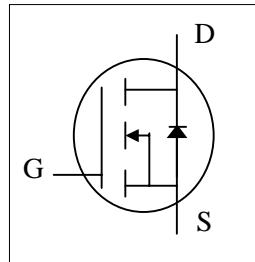


Simple Drive Requirement

Isolation Full Package

Fast Switching Characteristics

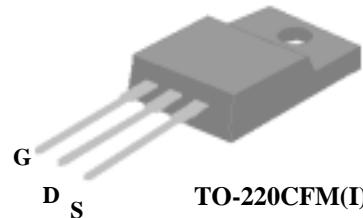
RoHS compliant



BV_{DSS}	900V
$R_{DS(ON)}$	7.2
I_D	1.9A

Description

The TO-220CFM package is universally preferred for all commercial-industrial applications. The device is suited for switch mode power supplies, AC-DC converters and high current high speed switching circuits.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	900	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D @ T_C=25$	Continuous Drain Current, $V_{GS} @ 10V$	1.9	A
$I_D @ T_C=100$	Continuous Drain Current, $V_{GS} @ 10V$	1.2	A
I_{DM}	Pulsed Drain Current ¹	6	A
$P_D @ T_C=25$	Total Power Dissipation	34.7	W
	Linear Derating Factor	0.28	W/
E_{AS}	Single Pulse Avalanche Energy ²	36	mJ
I_{AR}	Avalanche Current	1.9	A
T_{STG}	Storage Temperature Range	-55 to 150	
T_J	Operating Junction Temperature Range	-55 to 150	

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Thermal Resistance Junction-case	Max. 3.6	/W
R_{thj-a}	Thermal Resistance Junction-ambient	Max. 62	/W



Electrical Characteristics@ $T_j=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	900	-	-	V
BV_{DSS}/T_j	Breakdown Voltage Temperature Coefficient	Reference to 25 , $I_D=1mA$	-	0.8	-	V/
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=0.85A$	-	-	7.2	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=1.9A$	-	2	-	S
I_{DSS}	Drain-Source Leakage Current ($T_j=25^\circ C$)	$V_{DS}=900V, V_{GS}=0V$	-	-	10	μA
	Drain-Source Leakage Current ($T_j=150^\circ C$)	$V_{DS}=720V, V_{GS}=0V$	-	-	100	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 30V$	-	-	± 100	nA
Q_g	Total Gate Charge ³	$I_D=1.9A$	-	12	20	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=540V$	-	2.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	4.7	-	nC
$t_{d(on)}$	Turn-on Delay Time ³	$V_{DD}=450V$	-	10	-	ns
t_r	Rise Time	$I_D=1.9A$	-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=10 , V_{GS}=10V$	-	18	-	ns
t_f	Fall Time	$R_D=236$	-	9	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	630	1000	pF
C_{oss}	Output Capacitance	$V_{DS}=25V$	-	40	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	4	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ³	$I_S=1.9A, V_{GS}=0V$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_S=1.9A, V_{GS}=0V,$	-	360	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	1.8	-	μC

Notes:

- 1.Pulse width limited by safe operating area.
- 2.Starting $T_j=25^\circ C$, $V_{DD}=50V$, $L=20mH$, $R_G=25$, $I_{AS}=1.9A$.
- 3.Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

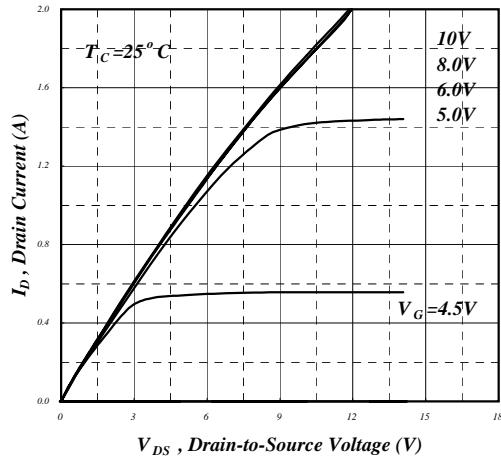


Fig 1. Typical Output Characteristics

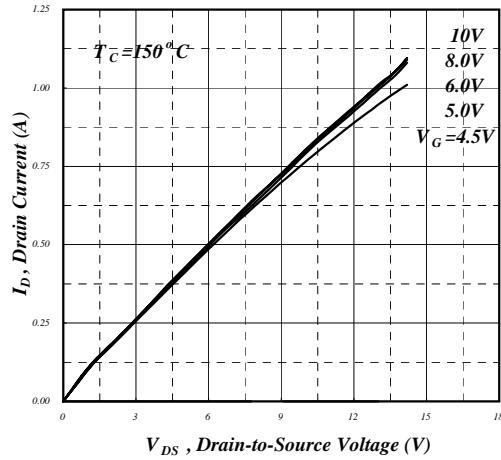


Fig 2. Typical Output Characteristics

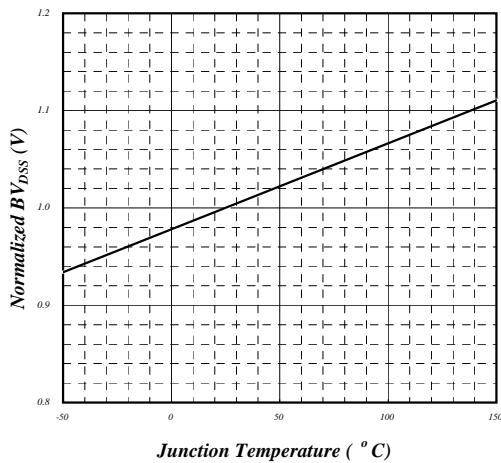
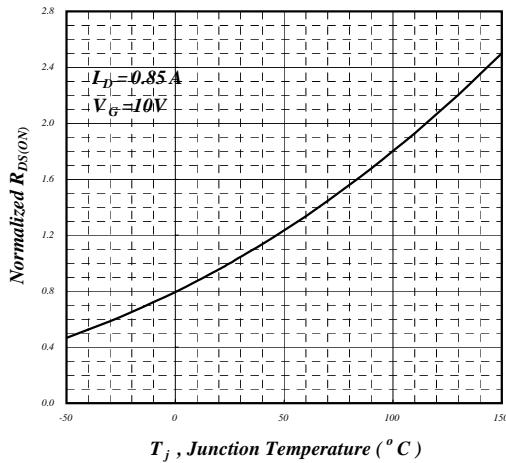
Fig 3. Normalized BV_{DSSS} v.s. Junction Temperature

Fig 4. Normalized On-Resistance v.s. Junction Temperature

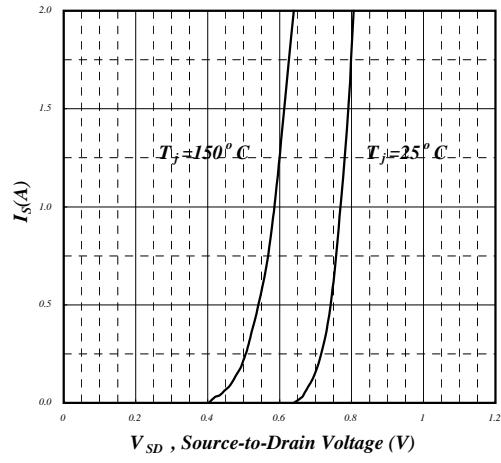


Fig 5. Forward Characteristic of Reverse Diode

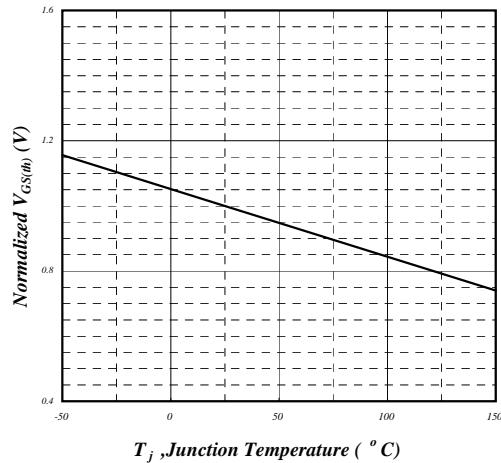


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



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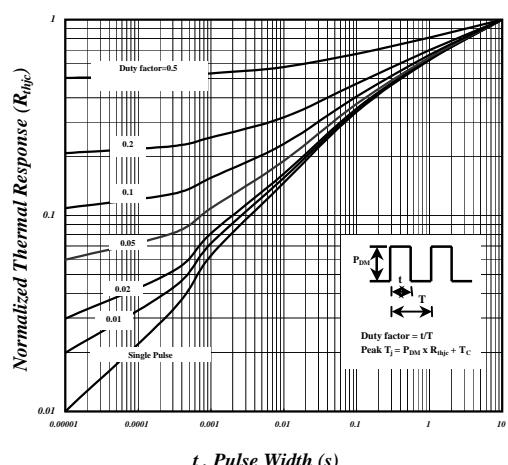
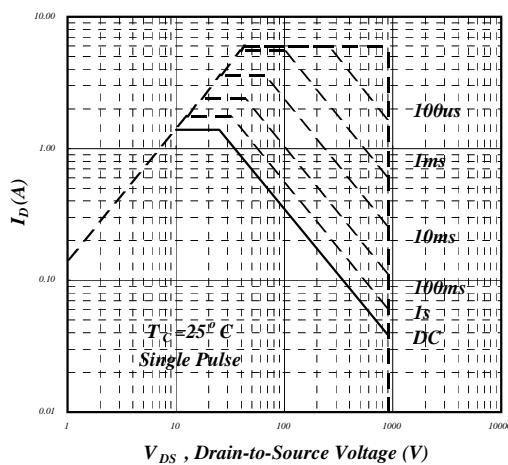
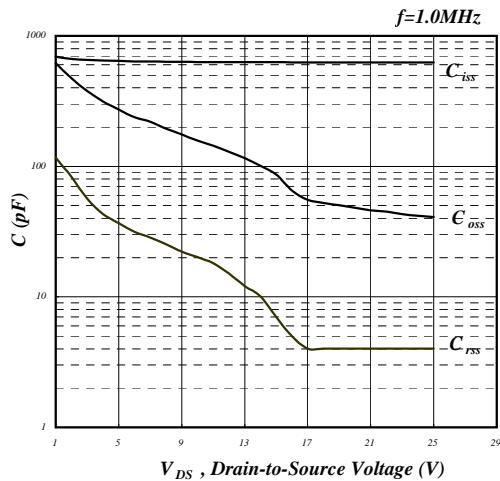
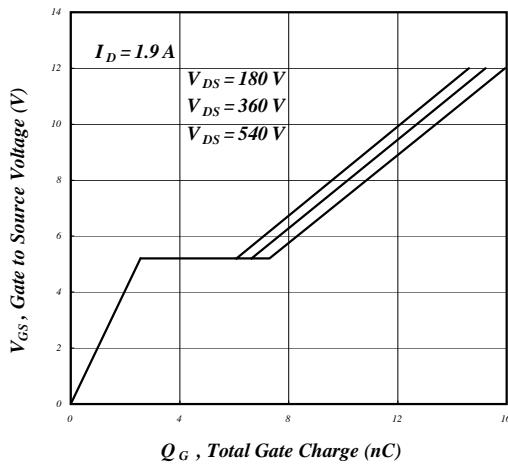


Fig 9. Maximum Safe Operating Area

Fig 10. Effective Transient Thermal Impedance

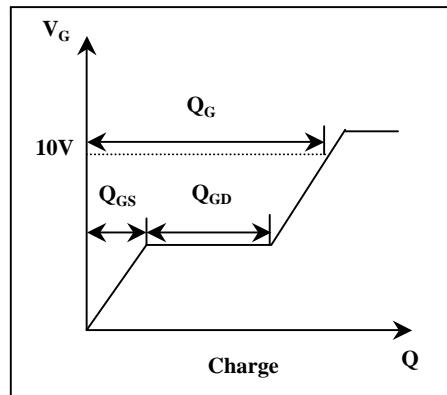
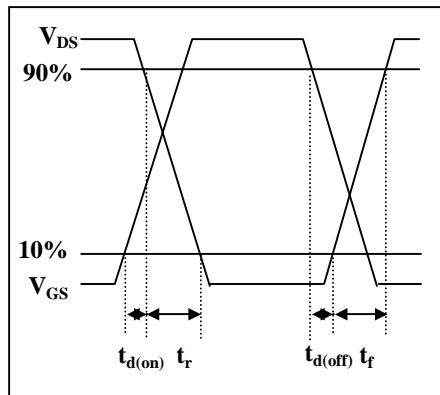


Fig 11. Switching Time Waveform

Fig 12. Gate Charge Waveform